Tool ID: 144
Tool Location: 107

Equipment Information Sheet

Plasma-Therm Takachi HDP-CVD

Manager: Jeremy Clark 607-254-6487
Backup: Philip Schneider 607-254-4931

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- User must remain in the lab during tool operation

USAGE RESTRICTIONS

- Do not modify recipes without prior staff approval
- Run "Clean with Endpoint" after running any depositions

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- 3 hour block reservation limit from 8AM - 6PM during weekdays

MATERIALS COMPATIBILITY CATEGORY

Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category

Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- If any polymer is present on wafer, 5mm of the edge must be removed
- Polymers must be fully cured at least 25C hotter than the deposition temperature
- No metals should be exposed to the plasma without staff approval

Last Updated: 05/11/2026